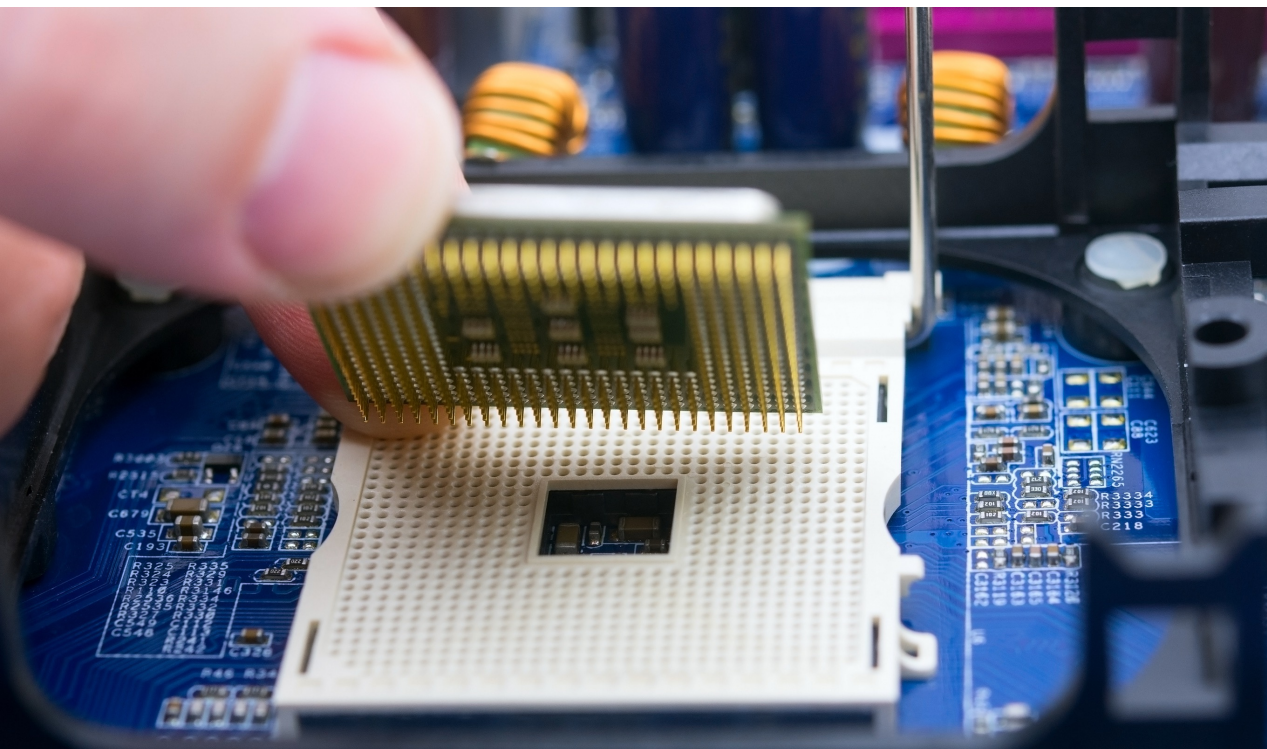


Selecting High Performance Plastics for Semiconductor Applications

Webinar Presented by Curbell Plastics



CURBELL
PLASTICS

Why Do We Care About the Semiconductor Market?

- Chips are everywhere!



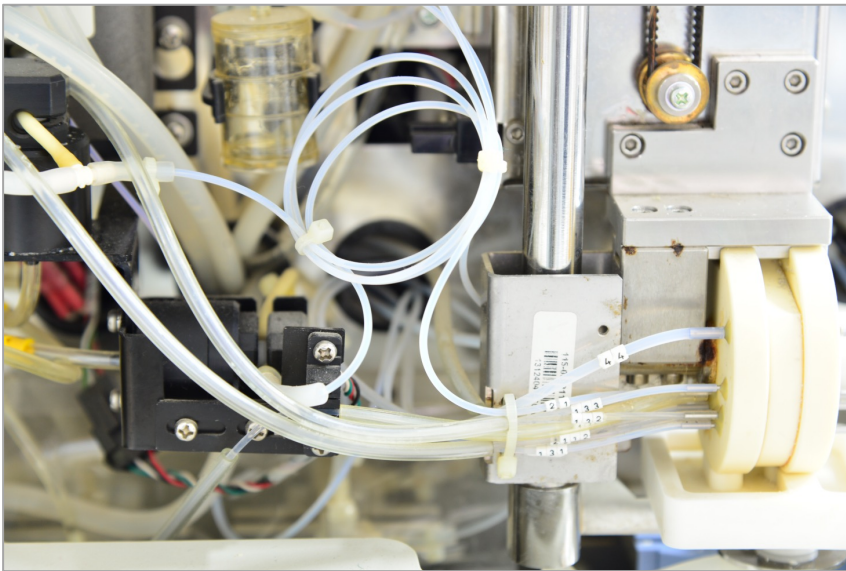
There are Many Steps Involved in Making Chips

- Many fabrication processes are involved in the manufacture of chips
 - Etch
 - CMP
 - Burn-In Testing
- Material requirements vary broadly between applications
 - Purity often critical

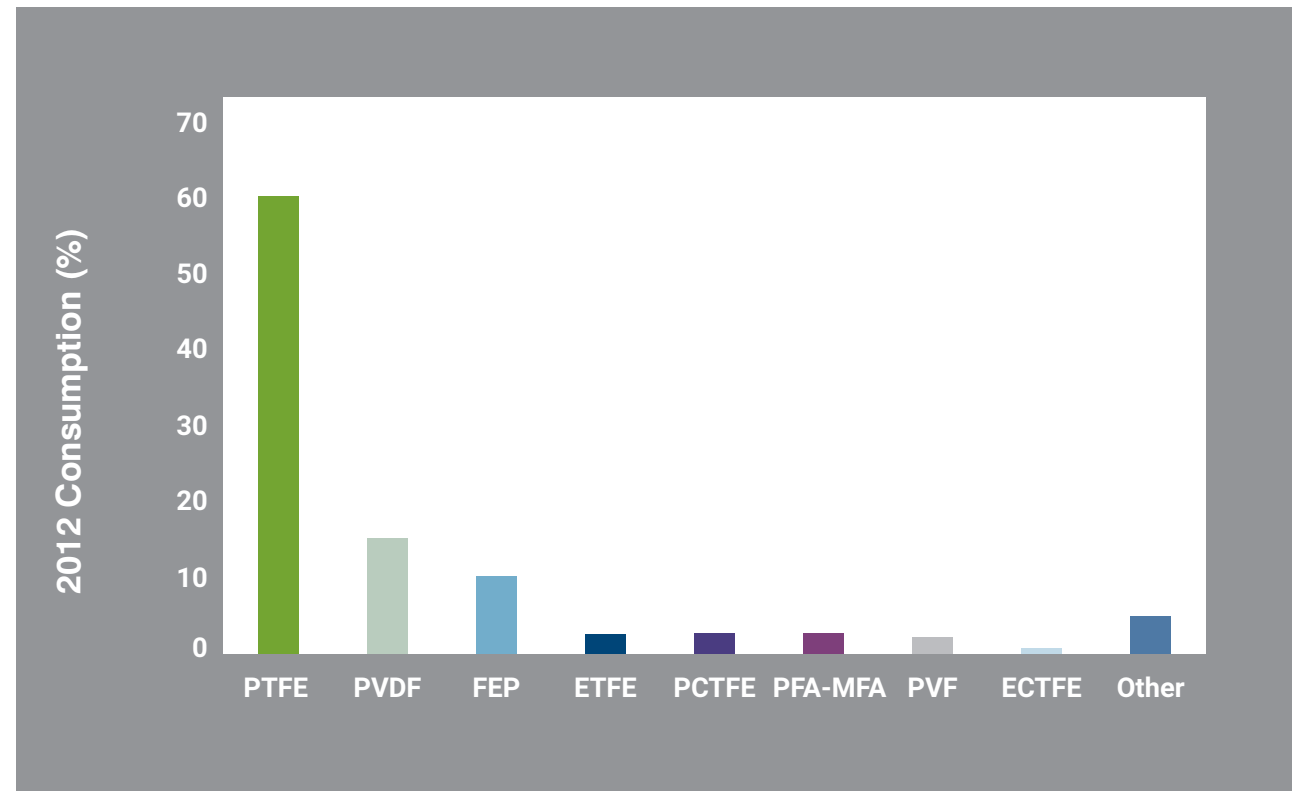


Fluoropolymers

- Fluoropolymers are known for their chemical inertness and purity



2012 Consumption Data of Various Fluoropolymers



Source: Fluoroplastics, Vol. 1

PTFE Chemical Compatibility

- There are NO chemicals on Curbell's website that PTFE is not compatible with

■ = Resistant
 ■ = Limited Resistance
 ▲ = Not Resistant
 * Resistance also dependent upon concentration, time, and temperature

AGENTS, CONCENTRATION: WEIGHT-%	ABS	Acetal (copolymer)	Acetal (homopolymer)	Noryl®	Nylon 6	PBT	PEK	PET	Polycarbonate	Polyethylene	Polypropylene (homopolymer)	PPS	PPSU (Radel® R)	PSU (Cyclar®)	PTFE	PVDF	Ulem®	Vespal® SP-1
Acetamide 50%	■	■	■	■	■	■	■	■	■	■	■	■	■	■	■	■	■	■
Acetic acid, aqueous solution 5%	■	■	■	■	■	■	■	■	■	■	■	■	■	■	■	■	■	■
Acetic acid, aqueous solution 10%	■	■	■	■	■	■	■	■	■	■	■	■	■	■	■	■	■	■
Acetic acid, concentrated	▲	▲	▲	▲	▲	▲	▲	▲	▲	■	■	■	■	■	■	■	■	■
Acetone	▲	■	■	■	■	■	■	■	■	■	■	■	■	■	■	■	■	■
Ammonia solution 10%	■	■	■	■	■	■	■	■	■	■	■	■	■	■	■	■	■	■
Anone	■	■	■	■	■	■	■	■	■	■	■	■	■	■	■	■	■	■
Benzene	▲	■	■	■	■	■	■	■	■	■	■	■	■	■	■	■	■	■
Benzine	■	■	■	■	■	■	■	■	■	■	■	■	■	■	■	■	■	■
Bitumen	■	■	■	■	■	■	■	■	■	■	■	■	■	■	■	■	■	■
Boric acid, aqueous solution 10%	■	■	■	■	■	■	■	■	■	■	■	■	■	■	■	■	■	■
Butyl acetate	■	■	■	■	■	■	■	■	■	■	■	■	■	■	■	■	■	■
Calcium chloride, solution 10%	■	■	■	■	■	■	■	■	■	■	■	■	■	■	■	■	■	■
Carbon tetrachloride	▲	■	■	■	■	■	■	■	■	■	■	■	■	■	■	■	■	■
Chlorobenzene	■	■	■	■	■	■	■	■	■	■	■	■	■	■	■	■	■	■
Chloroform	▲	■	■	■	■	■	■	■	■	■	■	■	■	■	■	■	■	■
Citric acid, aqueous solution 10%	■	■	■	■	■	■	■	■	■	■	■	■	■	■	■	■	■	■
Clophen A60, 50%	■	■	■	■	■	■	■	■	■	■	■	■	■	■	■	■	■	■
Cupric sulphate 10%	■	■	■	■	■	■	■	■	■	■	■	■	■	■	■	■	■	■
Cyclohexane	■	■	■	■	■	■	■	■	■	■	■	■	■	■	■	■	■	■
Cyclohexanone	■	■	■	■	■	■	■	■	■	■	■	■	■	■	■	■	■	■
Decalin	■	■	■	■	■	■	■	■	■	■	■	■	■	■	■	■	■	■
Diesel Oil	■	■	■	■	■	■	■	■	■	■	■	■	■	■	■	■	■	■
Dimethyl formamide	■	■	■	■	■	■	■	■	■	■	■	■	■	■	■	■	■	■
Diocetyl phthalate	■	■	■	■	■	■	■	■	■	■	■	■	■	■	■	■	■	■
Dioxane	■	■	■	■	■	■	■	■	■	■	■	■	■	■	■	■	■	■
Edible fats, Edible oils	■	■	■	■	■	■	■	■	■	■	■	■	■	■	■	■	■	■
Ethanol 96%	■	■	■	■	■	■	■	■	■	■	■	■	■	■	■	■	■	■
Ethyl acetate	■	■	■	■	■	■	■	■	■	■	■	■	■	■	■	■	■	■
Ethyl ether	■	■	■	■	■	■	■	■	■	■	■	■	■	■	■	■	■	■
Ethylene chloride	■	■	■	■	■	■	■	■	■	■	■	■	■	■	■	■	■	■
Formaldehyde, aqueous solution 30%	■	■	■	■	■	■	■	■	■	■	■	■	■	■	■	■	■	■
Formamide	■	■	■	■	■	■	■	■	■	■	■	■	■	■	■	■	■	■
Formic acid, aqueous solution 10%	■	■	■	■	■	■	■	■	■	■	■	■	■	■	■	■	■	■

Partially-Fluorinated vs. Fully-Fluorinated Materials

- Partially-fluorinated materials tend to exhibit enhanced permeation resistance relative to fully-flourinated

	PTFE	PFA	FEP	ETFE	CTFE	ECTFE	PVDF
Water Vapor g/m ² .d.bar	5	8	1	2	1	2	2
Air cm ³ /m ² .d.bar	2000	1150	600	175	X	40	7
Oxygen cm ³ /m ² .d.bar	1500	X	2900	350	60	100	20
Nitrogen cm ³ /m ² .d.bar	500	X	1200	120	10	40	30
Helium cm ³ /m ² .d.bar	3500	17000	18000	3700	X	3500	600
Carbon Dioxide cm ³ /m ² .d.bar	15000	7000	4700	1300	150	400	100

Data published in 1980 Kunstsoffee paper entitled Fluorocarbon Films-Present Situation and Future Outlook.
X = Not tested.

Not All Plastics Meet Stringent Flammability Standards

- FM4910 is the flammability standard created by the Factory Mutual Insurance Company for materials used in clean rooms
 - Common requirement for wet benches and tank materials
- Example FM4910 listed materials
 - Fluoropolymers such as PVDF, ECTFE, PFA
 - Specific grades of PP, PVC, and CPVC



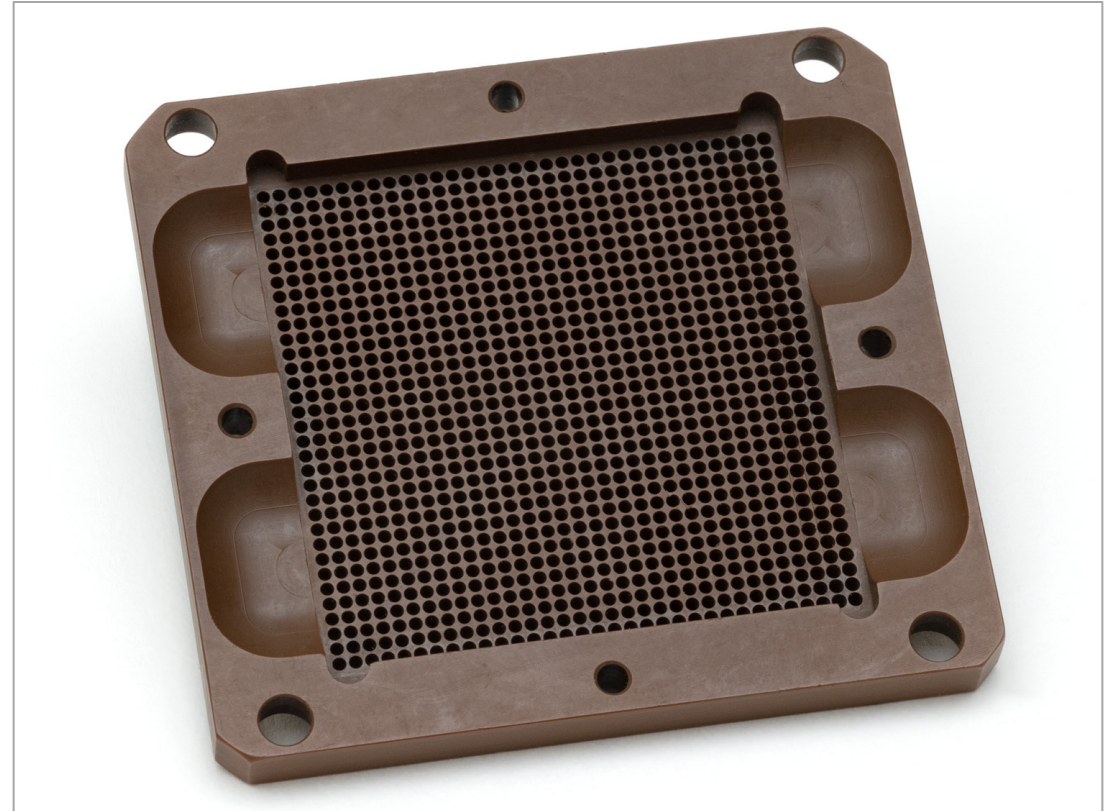
Electrical Properties of Plastics Can Be Tailored with Fillers

SURFACE RESISTIVITY RANGES FOR ESD PLASTICS				
	Conductive Plastics	Static Dissipative Plastics	Antistatic Plastics	Unfilled Plastics
Surface Resistivity Range (Ohms/sq)	10^1 to 10^6	10^6 to 10^9	10^9 to 10^{12}	$>10^{12}$

- Unfilled plastics and laminates like GPO-3 are widely used for electrical insulating applications
- Fillers can be added to polymeric materials to modify their electrical conductance properties
 - Often dealing with carbon (or graphite), but hygroscopic fillers or more conductive substances such as metallic fibers are used

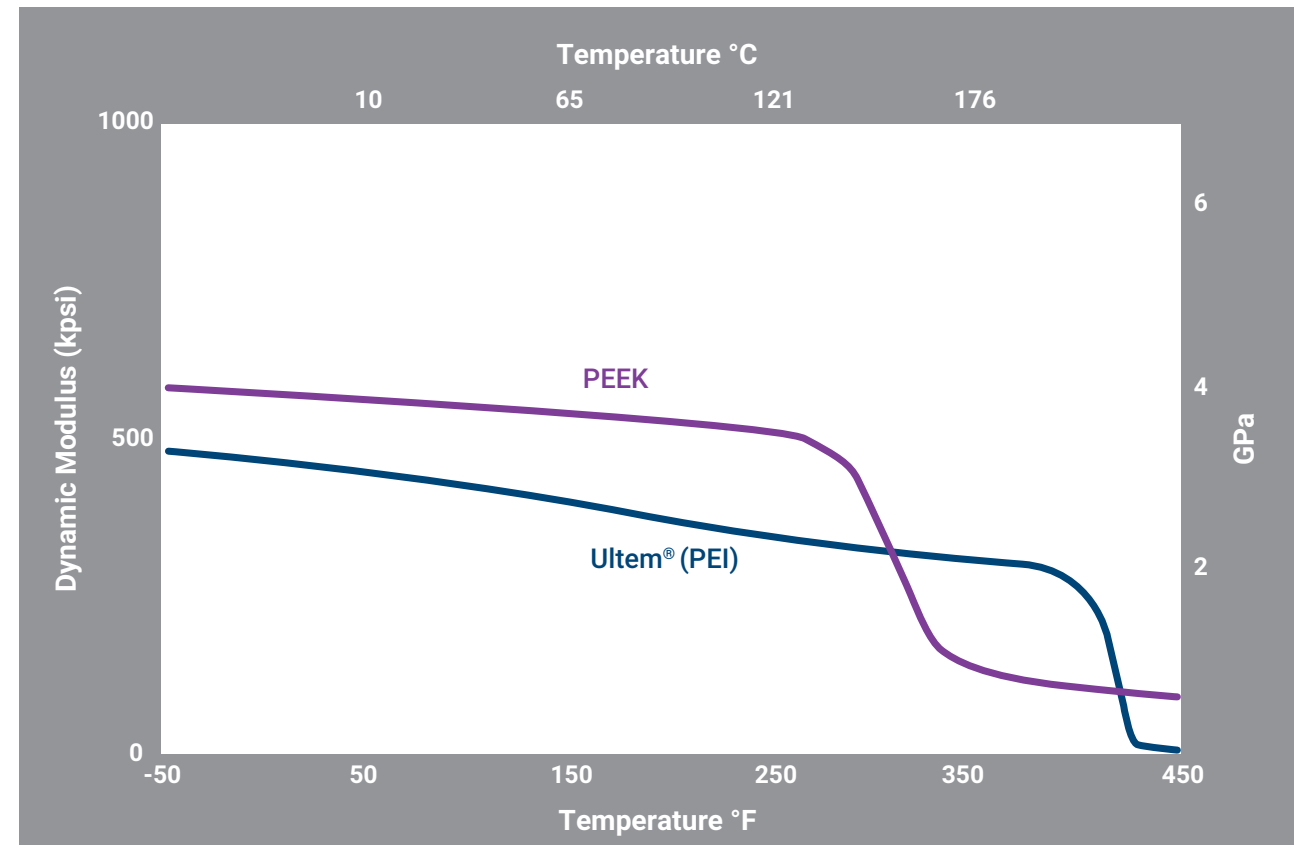
Challenge – Maintaining Dimensional Stability

- Maintaining dimensional stability is a common challenge for precision plastic components
 - Components with ultra-precise tolerance requirements, such as test sockets, require extremely stable materials
 - Traditionally, filled plastics, such as ceramic-filled PEEK, have been utilized, but with extremely precise features, their behavior can prove unpredictable



Temperature – Amorphous vs. Semi-Crystalline Materials

- Amorphous and semi-crystalline materials behave differently with respect to temperature



Directionality Induced by Manufacturing Process

SEMI-CRYSTALLINE DIRECTIONALITY EXAMPLE BELOW T_g		
Material	CTE - Flow Direction, Below T_g	CTE Average, Below T_g (all directions)
PEEK 450G (Unfilled)	$4.5 \times 10^{-5}/^{\circ}\text{C}$	$5.5 \times 10^{-5}/^{\circ}\text{C}$
PEEK 450GL30 (30% GF)	$1.8 \times 10^{-5}/^{\circ}\text{C}$	$4.5 \times 10^{-5}/^{\circ}\text{C}$

SEMI-CRYSTALLINE DIRECTIONALITY EXAMPLE ABOVE T_g		
Material	CTE - Flow Direction, Above T_g	CTE Average, Above T_g (all directions)
PEEK 450G (Unfilled)	$12.0 \times 10^{-5}/^{\circ}\text{C}$	$14.0 \times 10^{-5}/^{\circ}\text{C}$
PEEK 450GL30 (30% GF)	$1.8 \times 10^{-5}/^{\circ}\text{C}$	$11.0 \times 10^{-5}/^{\circ}\text{C}$

Sources: Victrex PEEK 450G and Victrex PEEK 450GL30 Datasheets, Victrex.

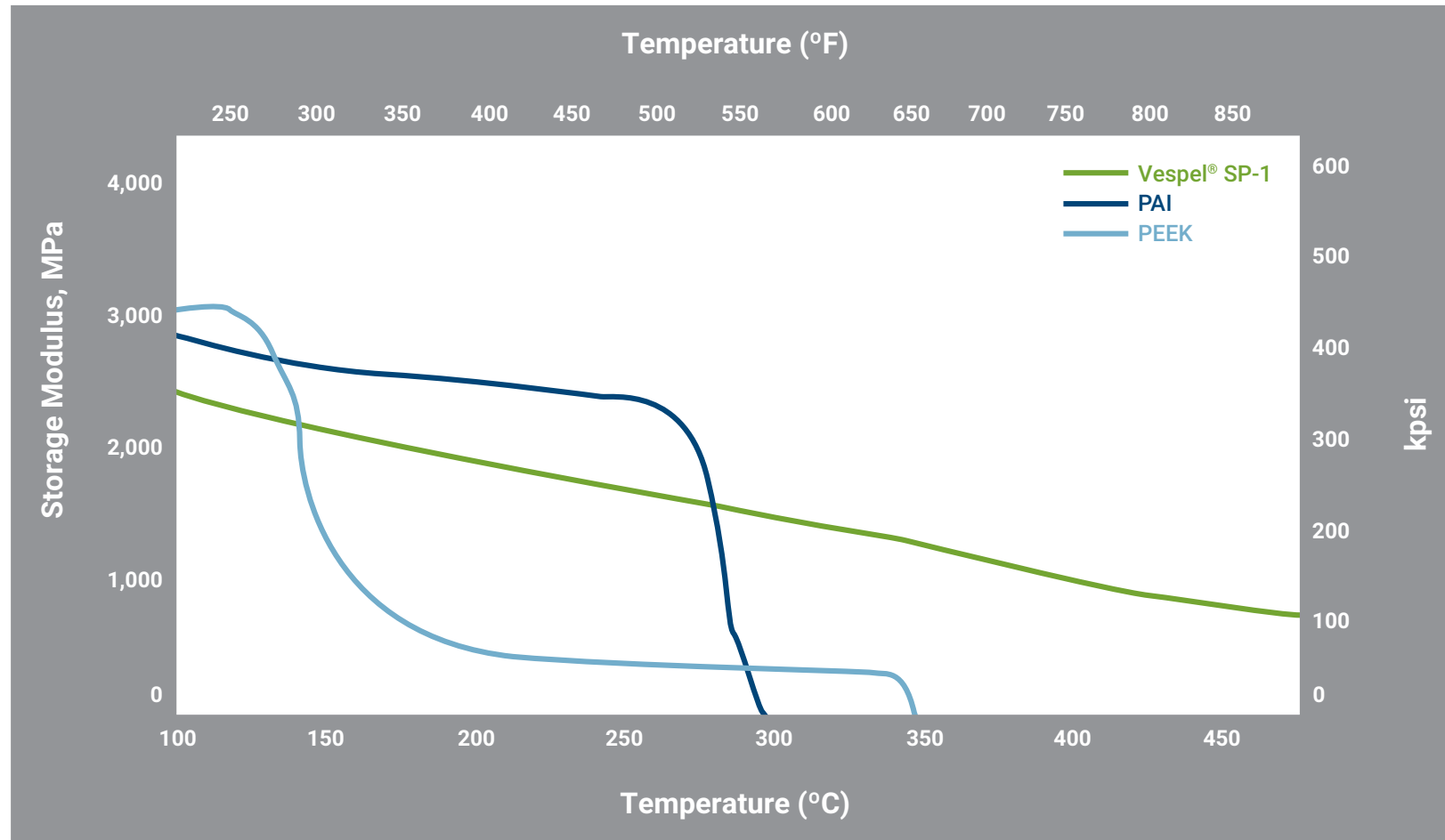
Other Popular Test Socket Materials

REPORTED TYPICAL PROPERTIES OF TORLON® 4203, VESPEL® SP-1, AND VESPEL® SCP-5000					
Material	Specific Gravity (ASTM D792)	Tensile Strength (ASTM D638)	Elongation, at break (ASTM D638)	Flexural Modulus (ASTM D790)	Water Absorption, 24 hours
Torlon® 4203	1.42	22,000 psi	7.6%	725,000 psi	0.33%
VespeI® SP-1	1.43	12,500 psi	7.5%	450,000 psi	0.24%
VespeI® SCP-5000	1.46	23,600 psi	7.5%	836,000 psi	0.08%

Sources: Torlon® PAI: Design Guide and Dupont™ VespeI® S Line: Design Handbook

Elevated Temperature Performance

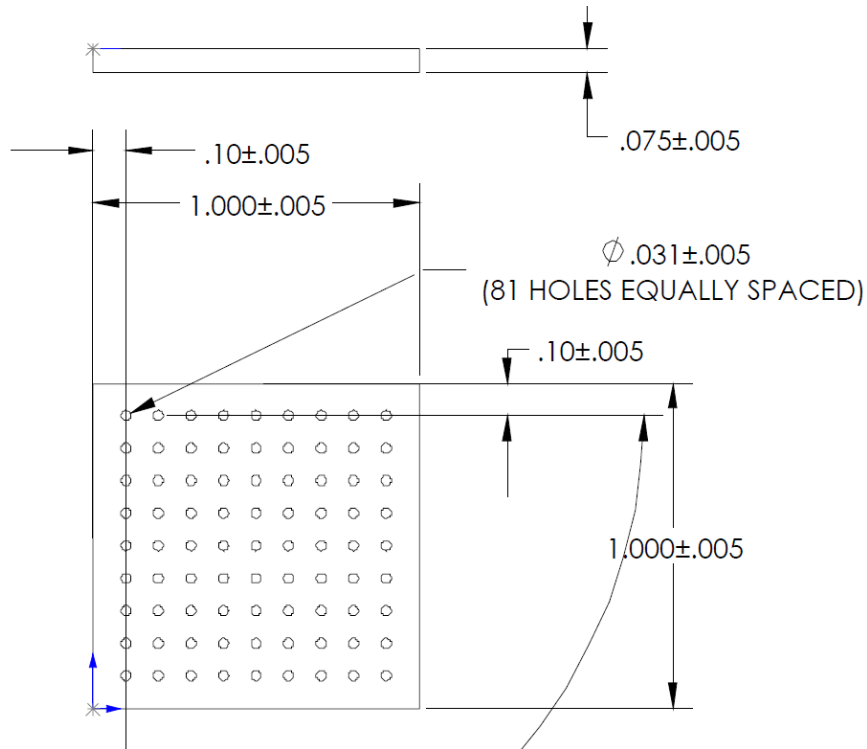
Modulus of PEEK, Torlon® 4203, and Vespel® SP-1 with Respect to Temperature



Source: Adapted from Dupont™ Vespel® Sealing Solutions

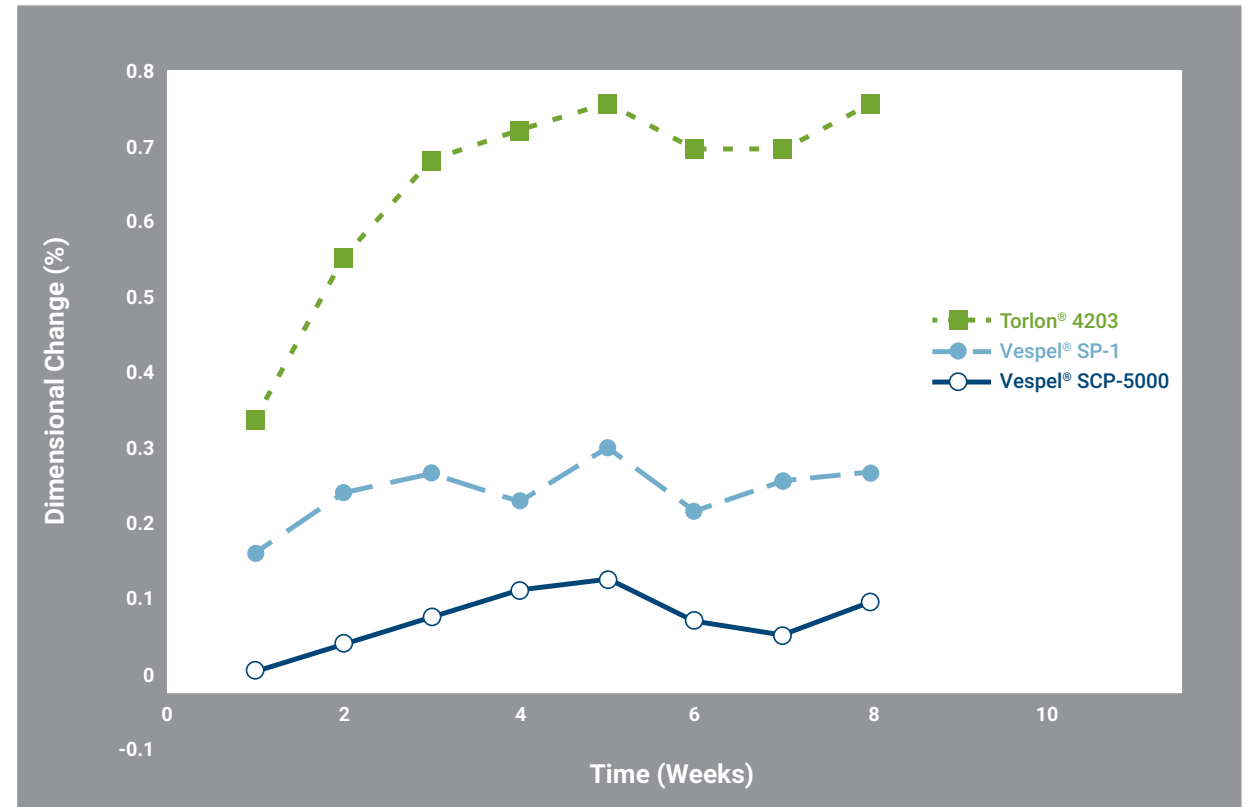
Torlon® vs. Vespel® for Precision Sockets

Moisture Sample with Holes
Example Design



Dimensional Change of 1" x 1" x 1/8" Coupons at 90% RH and 100°F with Respect to Time

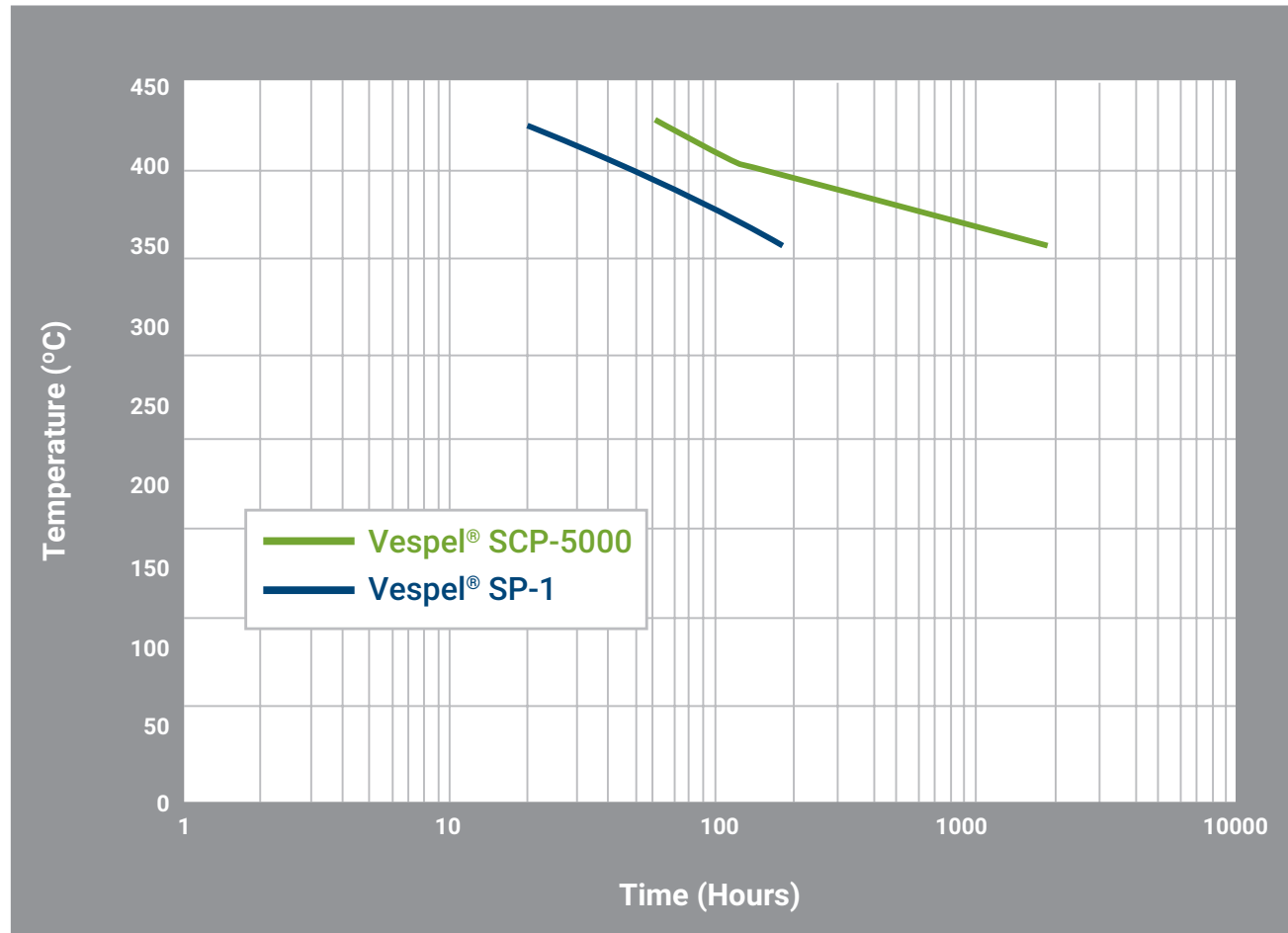
Dimensional Change vs. Exposure Time
100°F/90%RH – 1" x 1" x 1/8" Coupon with Holes



Source: Kane, Paul, and Joy Bloom (above), BiTS Workshop. 2004 (right)

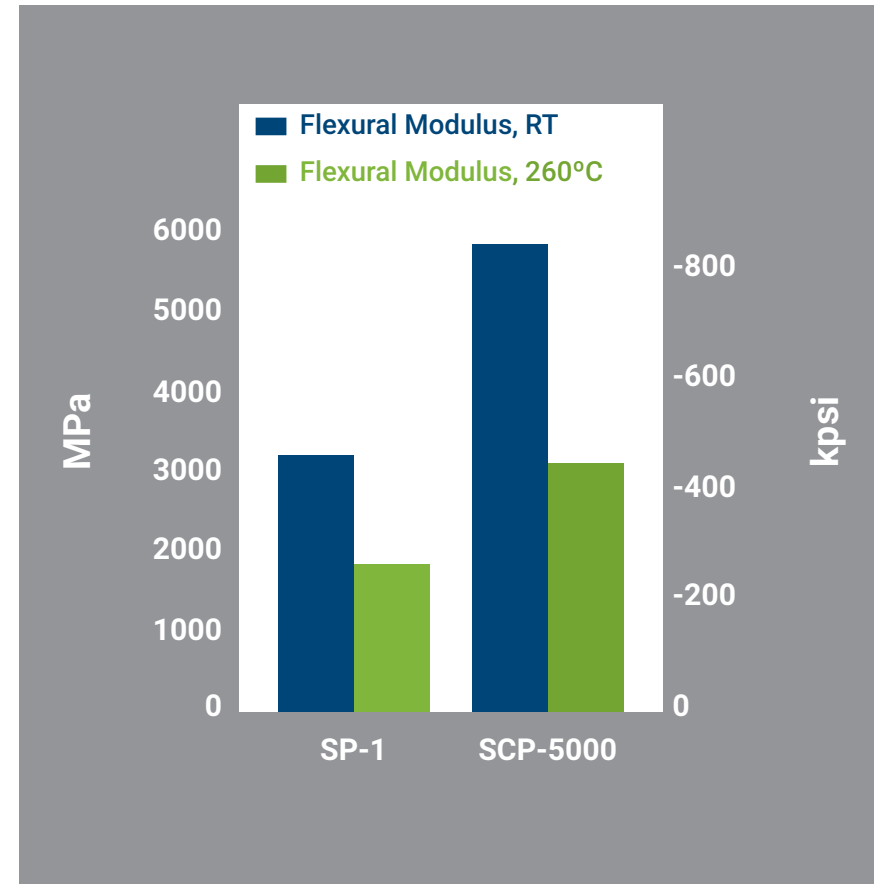
Vespe[®] SP vs. Vespe[®] SCP Thermal Stability

Time to 50% Reduction in Tensile Strength of Vespe[®] Materials Due to Heat Aging



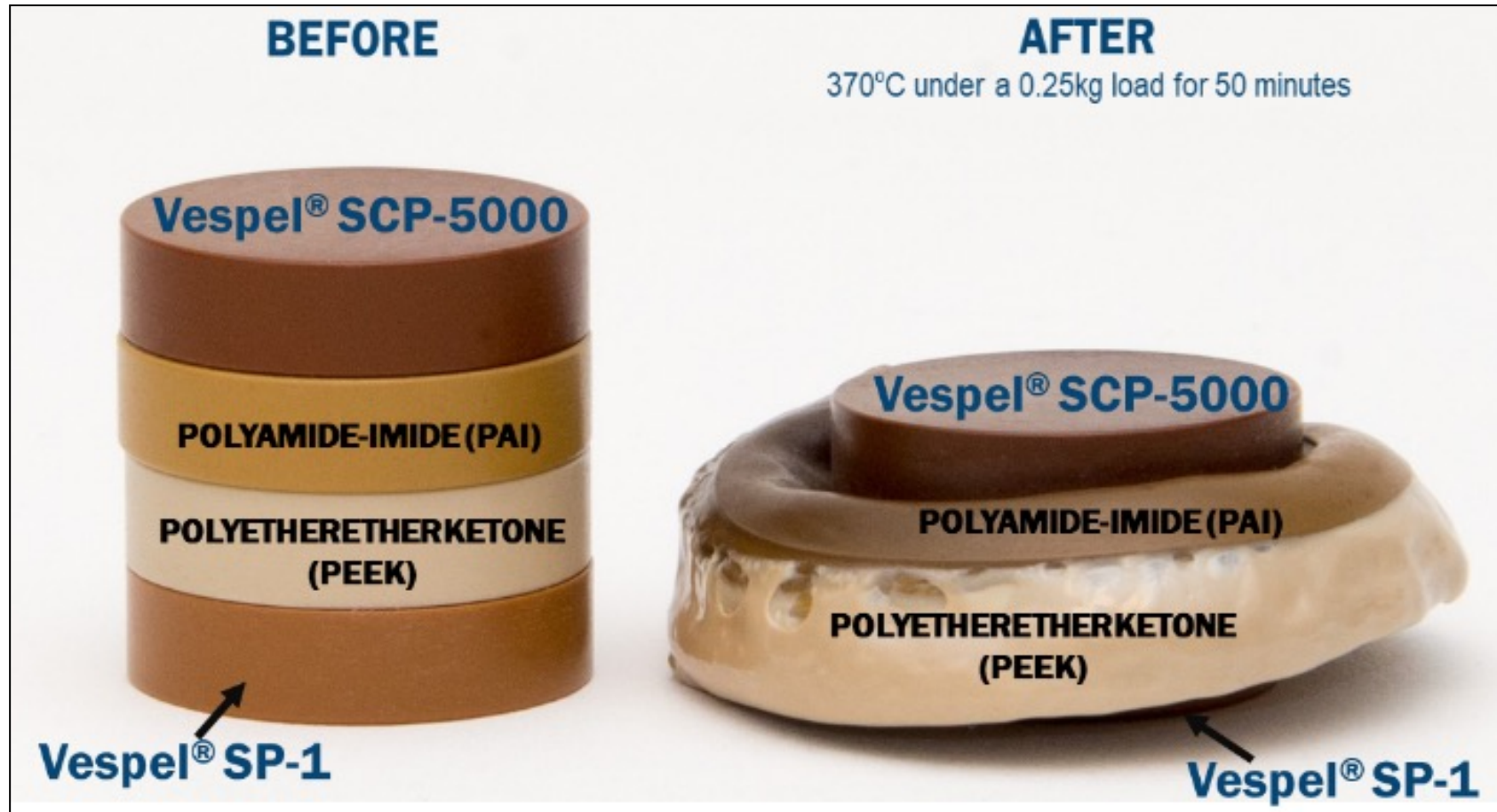
Source: Dupont[™] Vespe[®] Parts & Shapes: SCP-5000 Technical Bulletin

Vespe[®] SCP-5000 Offers Increased Strength / Stiffness



Source: Adapted from Dupont[™] Vespe[®] SCP Shapes Family of Products

Conclusion: Higher-Priced Materials Can Reduce Costs

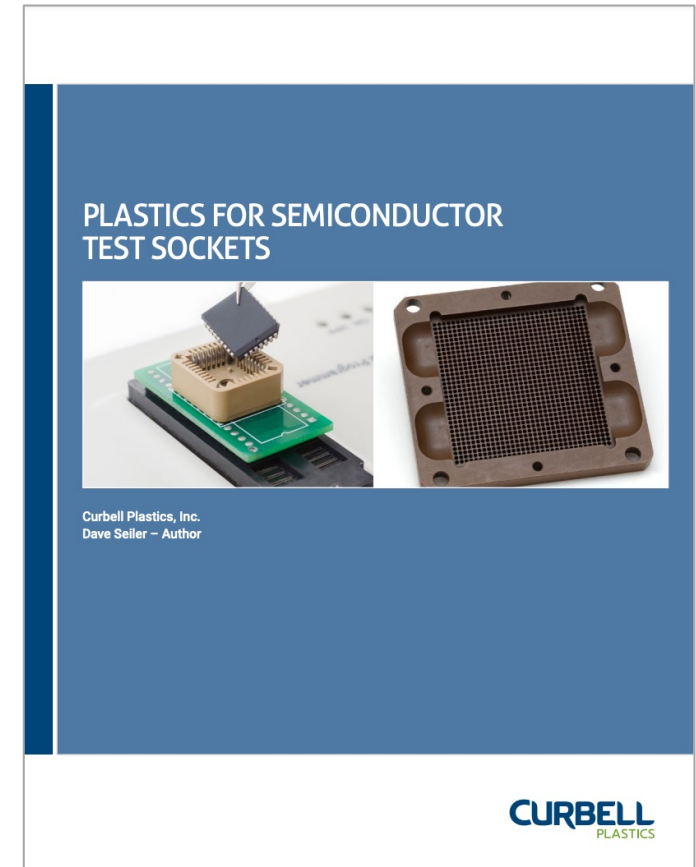


Source: [Dupont™ VespeL[®] High Performance Parts - Taking the Heat Video](#)

Test Socket Application White Paper

For information about plastic materials for today's test socket applications, read our white paper:

[*Plastics for Semiconductor Test Sockets*](#)



Thank You for Your Time Today! Questions?



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- Access the **Ask a Plastics Expert** form on curbellplastics.com for help with your applications
- Call Curbell Plastics at: 888-287-2355

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